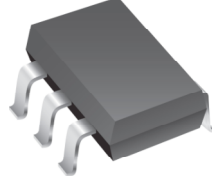


MATERIAL DECLARATION SHEET



Material Number	CDSOT23 Series			
Product Line	Diode Products			
Compliance Date	1 Jan 2006			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Frame	Lead Frame	0.0257	Copper	7440-50-8	95	40.770	42.8
				Tin	7440-31-5	5	2.0600	
2	Die	Silicon	0.014340	Silicon	7440-21-3	97	23.420	23.9
				Other non-regulated materials		3	0.4780	
3	Gold Bond Wire	Conductor	0.000352	Gold	7440-57-5	100	0.5867	0.6
4	Silver Paste	Die Attach	0.000808	Tin	7440-31-5	96	1.05	1.3
				Silver	7440-22-4	3.5	0.235	
				Copper	7440-50-8	0.5	0.075	
5	Molding Component	Outer	0.018840	Silica fused	60676-86-0	85	26.690	31.4
				Brominated Epoxy resin	68928-70-1	10	3.1400	
				Phenol resin	29690-62-2	5	1.8840	
		Total weight	0.060000					

This Document was updated on: 18-March 2009

MATERIAL DECLARATION SHEET



Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.